

TELECOM EQUIPMENT PROTECTION: TRISIL™

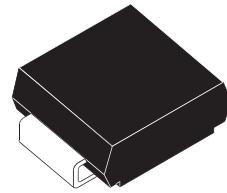
FEATURES

- Bidirectional crowbar protection
- Voltage range from 8V to 262V
- Low capacitance from 30 pF to 45pF typ @ 50V
- Low leakage current : $I_R = 2 \mu\text{A}$ max
- Holding current: $I_H = 150 \text{ mA}$ min
- Repetitive peak pulse current :
 $I_{PP} = 100 \text{ A}$ (10/1000μs)

MAIN APPLICATIONS

Any sensitive equipment requiring protection against lightning strikes and power crossing:

- Analog and digital line cards
(xDSL, T1/ E1, ISDN...)
- Terminals (phone, fax, modem...) and central office equipment

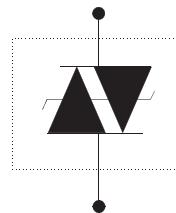


SMB
(JEDEC DO-214AA)

DESCRIPTION

The SMP100LC-xxx series is a low capacitance transient surge arrester designed for the protection of high debit rate communication equipment. Its low capacitance avoids any distortion of the signal and is compatible with digital line cards (xDSL, T1/E1, ISDN...).

SCHEMATIC DIAGRAM



BENEFITS

Trisils are not subject to ageing and provide a fail safe mode in short circuit for a better protection. They are used to help equipment to meet main standards such as UL1950, IEC950 / CSA C22.2 and UL1459. They have UL94 V0 approved resin. SMB package is JEDEC registered (DO-214AA). Trisils are UL497B approved (file: E136224) and comply with the following standards GR-1089 Core, ITU-T-K20/K21, VDE0433, VDE0878, IEC61000-4-5 and FCC part 68.

IN COMPLIANCE WITH THE FOLLOWING STANDARDS

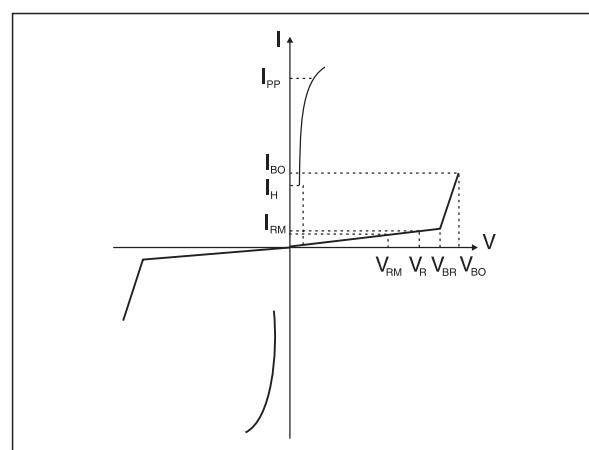
| STANDARD | Peak Surge Voltage (V) | Voltage Waveform | Required peak current (A) | Current waveform | Minimum serial resistor to meet standard (Ω) |
|-------------------------------------|------------------------|----------------------------------|--|----------------------------------|---|
| GR-1089 Core First level | 2500 1000 | 2/10 μ s 10/1000 μ s | 500 100 | 2/10 μ s 10/1000 μ s | 0 0 |
| GR-1089 Core Second level | 5000 | 2/10 μ s | 500 | 2/10 μ s | 0 |
| GR-1089 Core Intra-building | 1500 | 2/10 μ s | 100 | 2/10 μ s | 0 |
| ITU-T-K20/K21 | 6000 1500 | 10/700 μ s | 150 37.5 | 5/310 μ s | 0 0 |
| ITU-T-K20 (IEC61000-4-2) | 8000 15000 | 1/60 ns | ESD contact discharge ESD air discharge | | 0 0 |
| VDE0433 | 4000 2000 | 10/700 μ s | 100 50 | 5/310 μ s | 0 0 |
| VDE0878 | 4000 2000 | 1.2/50 μ s | 100 50 | 1/20 μ s | 0 0 |
| IEC61000-4-5 | 4000 4000 | 10/700 μ s 1.2/50 μ s | 100 100 | 5/310 μ s 8/20 μ s | 0 0 |
| FCC Part 68, lightning surge type A | 1500 800 | 10/160 μ s 10/560 μ s | 200 100 | 10/160 μ s 10/560 μ s | 0 0 |
| FCC Part 68, lightning surge type B | 1000 | 9/720 μ s | 25 | 5/320 μ s | 0 |

THERMAL RESISTANCES

| Symbol | Parameter | Value | Unit |
|---------------|--|-------|----------------------|
| $R_{th(j-a)}$ | Junction to ambient with recommended footprint | 100 | $^{\circ}\text{C/W}$ |
| $R_{th(j-l)}$ | Junction to leads | 20 | $^{\circ}\text{C/W}$ |

ELECTRICAL CHARACTERISTICS ($T_{\text{amb}} = 25^{\circ}\text{C}$)

| Symbol | Parameter |
|----------|-----------------------------|
| V_{RM} | Stand-off voltage |
| I_{RM} | Leakage current at V_{RM} |
| V_R | Continuous reverse voltage |
| I_R | Leakage current at V_R |
| V_{BR} | Breakdown voltage |
| V_{BO} | Breakover voltage |
| I_H | Holding current |
| I_{BO} | Breakover current |
| I_{PP} | Peak pulse current |
| C | Capacitance |



ABSOLUTE RATINGS ($T_{amb} = 25^\circ\text{C}$)

| Symbol | Parameter | Value | Unit | |
|--------------------|--|--|--------------------------------------|----------------------|
| I_{pp} | Repetitive peak pulse current: 10/1000 μs 8/20 μs 10/560 μs 5/310 μs 10/160 μs 1/20 μs 2/10 μs | 100 250 120 150 200 250 500 | A | |
| I_{FS} | Fail-safe mode : maximum current (note 1) | 8/20 μs | 5 | kA |
| I_{TSM} | Non repetitive surge peak on-state current (Sinusoidal) | $t = 20\text{ms}$ $t = 16.6\text{ms}$ $t = 0.2\text{s}$ $t = 2\text{s}$ | 55 60 25 12 | A |
| I^2t | I^2t value for fusing | $t = 16.6\text{ms}$ $t = 20\text{ms}$ | 30 | A^2s |
| T_L | Maximum lead temperature for soldering during 10s | 260 | $^\circ\text{C}$ | |
| T_{stg} T_j | Storage temperature range Maximum junction temperature | - 55 to + 150 150 | $^\circ\text{C}$ $^\circ\text{C}$ | |

Note 1: in fail safe mode, the device acts as a short circuit.

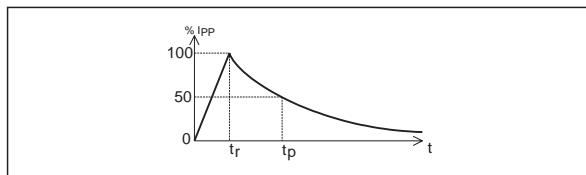
Repetitive peak pulse current

t_r : rise time (μs)

t_p : pulse duration time (μs)

ex: Pulse waveform 10/1000 μs

$t_r = 10\mu\text{s}$ $t_p = 1000\mu\text{s}$

**ELECTRICAL PARAMETERS** ($T_{amb} = 25^\circ\text{C}$)

| Type | $I_{RM} @ V_{RM}$ max. | | $I_R @ V_R$ max. Note 1 | | Dynamic $V_{BO} @ I_{BO}$ max. max Note 2 | | Static $V_{BO} @ I_{BO}$ max. max Note 3 | | I_H min. Note 4 | C typ. Note 5 | C typ. Note 6 |
|--------------|---------------------------|-----|-------------------------------|-----|--|-----|---|-----|-------------------------|---------------------|---------------------|
| | μA | V | μA | V | V | mA | V | mA | mA | pF | pF |
| SMP100LC-8 | 2 | 6 | 50 | 8 | 25 | 800 | 15 | 800 | 50 (typ) | NA | 75 |
| SMP100LC-25 | | 22 | | 25 | 40 | | 35 | | 150 | NA | 65 |
| SMP100LC-35 | | 32 | | 35 | 55 | | 55 | | 150 | NA | 55 |
| SMP100LC-65 | | 55 | | 65 | 85 | | 85 | | 150 | 45 | 90 |
| SMP100LC-90 | | 81 | | 90 | 120 | | 125 | | 150 | 40 | 80 |
| SMP100LC-120 | | 108 | | 120 | 155 | | 160 | | 150 | 35 | 75 |
| SMP100LC-140 | | 120 | | 140 | 185 | | 190 | | 150 | 30 | 65 |
| SMP100LC-160 | | 144 | | 160 | 210 | | 220 | | 150 | 30 | 65 |
| SMP100LC-200 | | 170 | | 200 | 265 | | 275 | | 150 | 30 | 60 |
| SMP100LC-230 | | 200 | | 230 | 300 | | 320 | | 150 | 30 | 60 |
| SMP100LC-270 | | 230 | | 262 | 350 | | 370 | | 150 | 30 | 60 |

Note 1: I_R measured at V_R guarantee $V_{BR} \geq V_R$

Note 2: See functional test circuit 1

Note 3: See test circuit 2

Note 4: See functional holding current test circuit 3

Note 5: $V_R = 50\text{V}$ bias, $VRMS=1\text{V}$, $F=1\text{MHz}$

Note 6: $V_R = 2\text{V}$ bias, $VRMS=1\text{V}$, $F=1\text{MHz}$

SMP100LC-xxx

Fig. 1: Non repetitive surge peak on-state current versus overload duration (T_j initial = 25 °C).

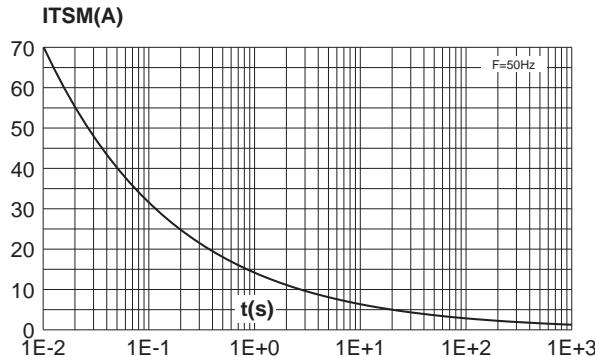


Fig. 3: Relative variation of holding current versus junction temperature .

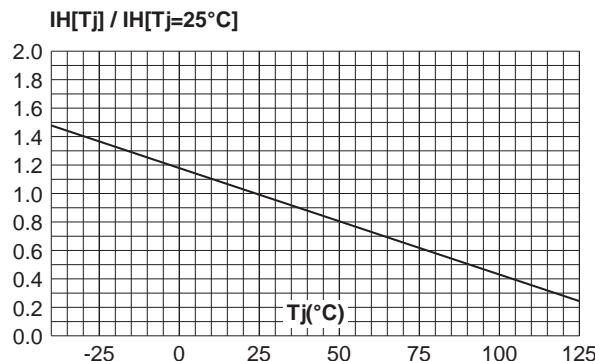


Fig. 5: Relative variation of leakage current versus junction temperature (typical values).

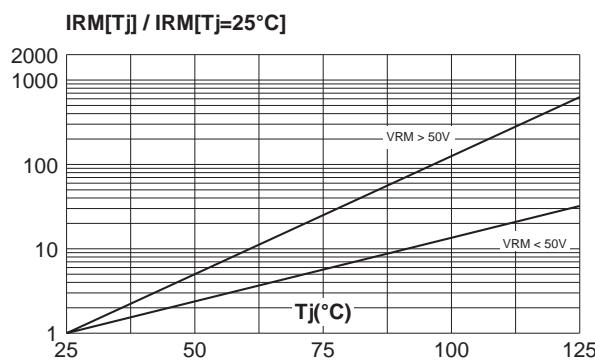


Fig. 2: On-state voltage versus on-state current (typical values)

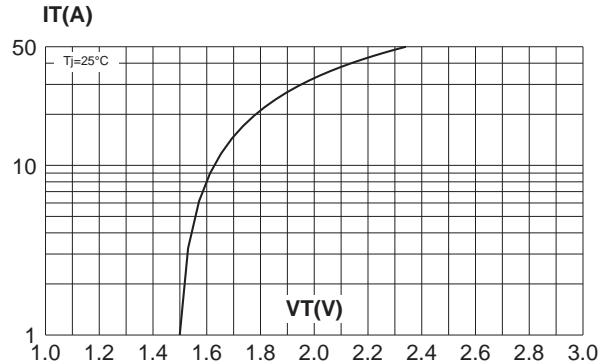


Fig. 4: Relative variation of breakdown voltage versus junction temperature.

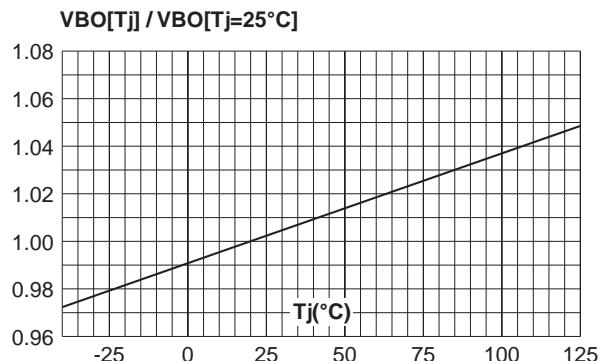


Fig. 6: Variation of thermal impedance junction to ambient versus pulse duration (Printed circuit board FR4, SCu=35μm, recommended pad layout).

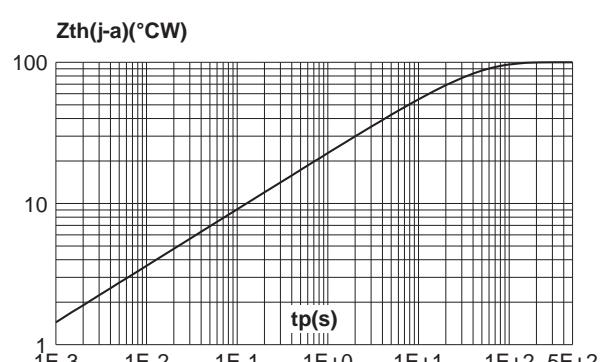
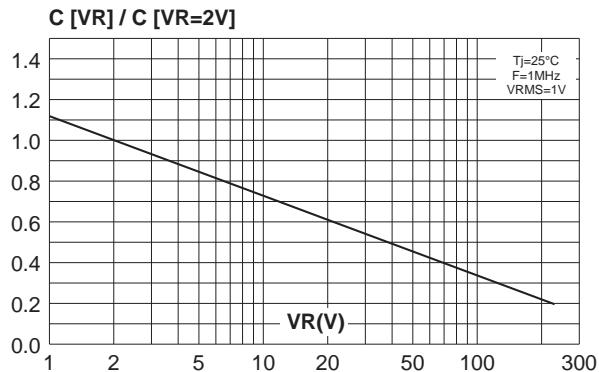
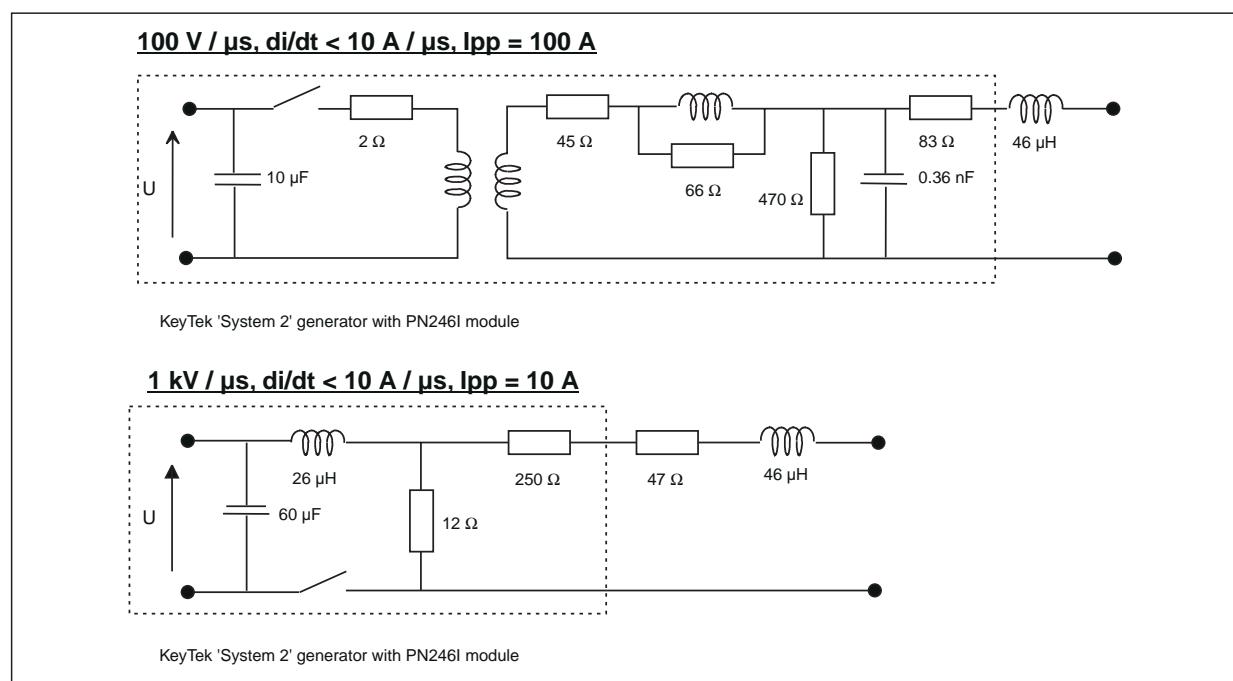
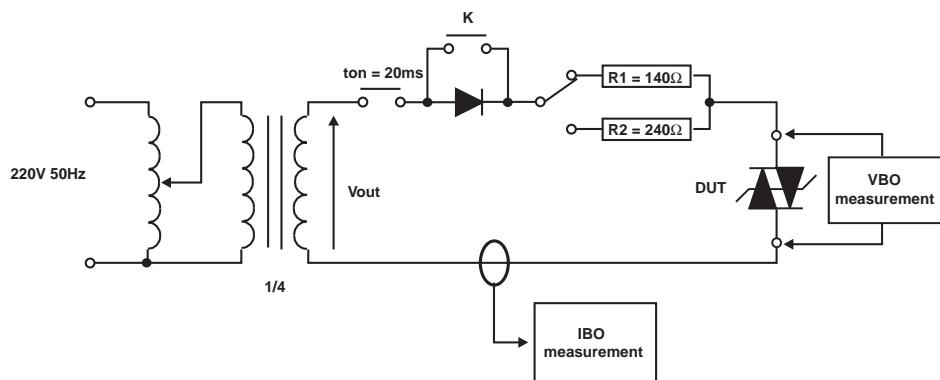


Fig. 7: Relative variation of junction capacitance versus reverse voltage applied (typical values).



TEST CIRCUIT 1 FOR DYNAMIC I_{BO} AND V_{BO} PARAMETERS



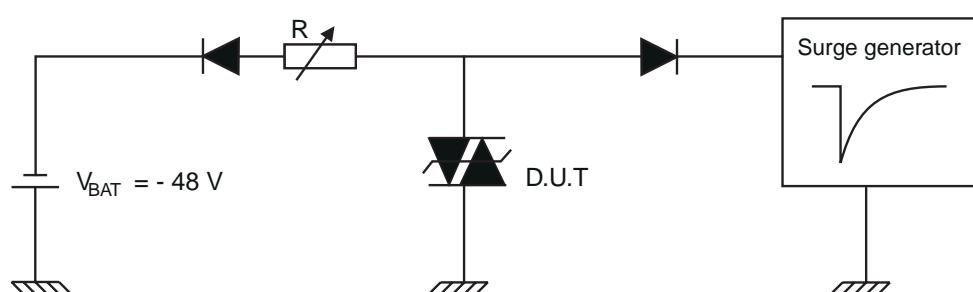
TEST CIRCUIT 2 FOR I_{BO} and V_{BO} parameters :**TEST PROCEDURE :**

Pulse test duration ($t_p = 20\text{ms}$):

- For Bidirectional devices = Switch K is closed
- For Unidirectional devices = Switch K is open.

V_{OUT} Selection

- Device with $V_{BO} < 200$ Volt
 - $V_{OUT} = 250 \text{ V}_{\text{RMS}}$, $R_1 = 140 \Omega$.
- Device with $V_{BO} \geq 200$ Volt
 - $V_{OUT} = 480 \text{ V}_{\text{RMS}}$, $R_2 = 240 \Omega$.

TEST CIRCUIT 3 FOR I_H PARAMETER

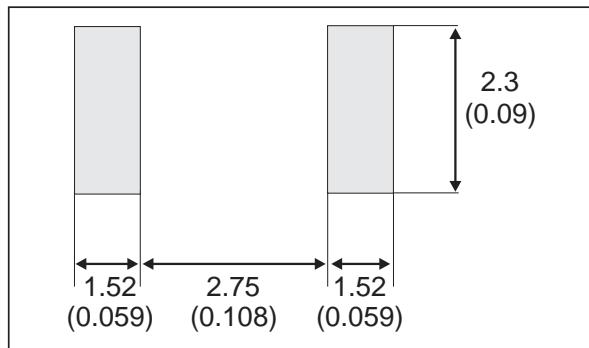
This is a GO-NO GO test which allows to confirm the holding current (I_H) level in a functional test circuit.

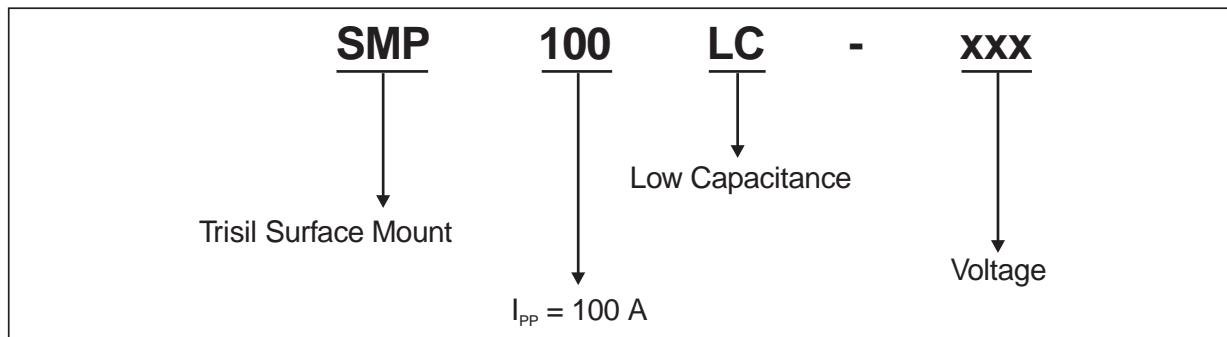
TEST PROCEDURE :

- Adjust the current level at the I_H value by short circuiting the D.U.T.
- Fire the D.U.T. with a surge current : $I_{pp} = 10\text{A}$, $10/1000 \mu\text{s}$.
- The D.U.T. will come back to the off-state within 50 ms max.

PACKAGE MECHANICAL DATA
SMB (Plastic)

| REF. | DIMENSIONS | | | |
|------|-------------|------|--------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A1 | 1.90 | 2.45 | 0.075 | 0.096 |
| A2 | 0.05 | 0.20 | 0.002 | 0.008 |
| b | 1.95 | 2.20 | 0.077 | 0.087 |
| c | 0.15 | 0.41 | 0.006 | 0.016 |
| E | 5.10 | 5.60 | 0.201 | 0.220 |
| E1 | 4.05 | 4.60 | 0.159 | 0.181 |
| D | 3.30 | 3.95 | 0.130 | 0.156 |
| L | 0.75 | 1.60 | 0.030 | 0.063 |

FOOT PRINT in millimeters (inches)

ORDER CODE

| Ordering type | Marking | Package | Weight | Base qty | Delivery mode |
|---------------|---------|---------|--------|----------|---------------|
| SMP100LC-8 | PL8 | SMB | 0.11g | 2500 | Tape & Reel |
| SMP100LC-25 | L25 | | | | |
| SMP100LC-35 | L35 | | | | |
| SMP100LC-65 | L06 | | | | |
| SMP100LC-90 | L09 | | | | |
| SMP100LC-120 | L12 | | | | |
| SMP100LC-140 | L14 | | | | |
| SMP100LC-160 | L16 | | | | |
| SMP100LC-200 | L20 | | | | |
| SMP100LC-230 | L23 | | | | |
| SMP100LC-270 | L27 | | | | |

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